

*W* at least one pair of positioning walls for positioning the electronic component, wherein  
*W* the at least one pair of positioning walls are inner wall faces of the base.

*B2* 12. (Twice Amended) A circuit board with a fixture, comprising;  
a fixture mounted on a circuit board, for placing an electronic component; and  
electrodes formed on the circuit board with the fixture,  
wherein the fixture comprises a movable pawl for fixing an electronic component by  
being brought into contact with a top face of the electronic component and at least one pair of  
positioning walls for positioning an electronic component,  
the at least one pair of positioning walls are inner wall faces of the fixture, and  
the electrodes are exposed between the at least one pair of positioning walls.

*B3* 20. (Twice Amended) An electronic-component mounted body, comprising:  
a circuit board with electrodes;  
a fixture; and  
an electronic component with electrodes,  
the electronic component being placed on a circuit board using the fixture, and  
bumps formed on the electrodes of the electronic component or on the electrodes on the  
circuit board,  
wherein the fixture comprises a movable pawl and at least one pair of positioning walls,  
the movable pawl fixes the electronic component to the circuit board,  
the at least one pair of positioning walls control a position of the electronic component in  
a direction parallel to a surface of the circuit board with the electronic component placed  
therebetween,  
the electrodes of the electronic component are connected to the electrodes on the circuit  
board formed between the at least one pair of positioning walls, and  
the bumps and the electrodes on which the bumps are not formed are connected to each  
other with a conductive material interposed therebetween.

30. (Twice Amended) A method of manufacturing an electronic-component mounted body, comprising:

providing a circuit board provided with a fixture and electrodes, the fixture having a moveable pawl and at least one pair of positioning walls, wherein the at least one pair of positioning walls are inner wall faces of the fixture,

the electrodes being formed to be exposed between the at least one pair of positioning walls; and

connecting electrodes of an electronic component and the electrodes on the circuit board by fitting the electronic component between the at least one pair of positioning walls and fixing the electronic component by the movable pawl, and

forming bumps on the electrodes of the electronic component or on the electrodes on the circuit board, the bumps and the electrodes on which the bumps are not formed are connected to each other with a conductive material interposed therebetween.

Please add new claims 34 and 35 as follows:

34. (New) The fixture according to claim 1, wherein the movable pawl has a flat surface facing downward, the flat surface being brought into contact with the top face of the electronic component.

35. (New) The circuit board with a fixture according to claim 12, wherein the movable pawl has a flat surface facing downward, the flat surface being brought into contact with the top face of the electronic component.